

**ABSTRACT**

A flexible interconnect substrate (1) comprises a tape-shaped base substrate (10) and a plurality of interconnect patterns (20) formed on the base substrate (10). The base substrate (10) has a plurality of first regions (44) set to be punched out, and second regions (45) between those first regions (44). Each of the second regions (45) has the material that forms the base substrate (10) is present in a central portion in the widthwise direction of the base substrate (10), and a low-bending-resistance portion (40) for ensuring that the second region (45) bends more readily than the adjacent first regions (44) in a direction in which the longitudinal axis of the base substrate (10) bends.

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